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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	121
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 34x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30835fjgp-u3

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1.3 Block Diagram

Figure 1.1 shows a block diagram of the M32C/83 Group (M32C/83, M32C/83T) microcomputer.

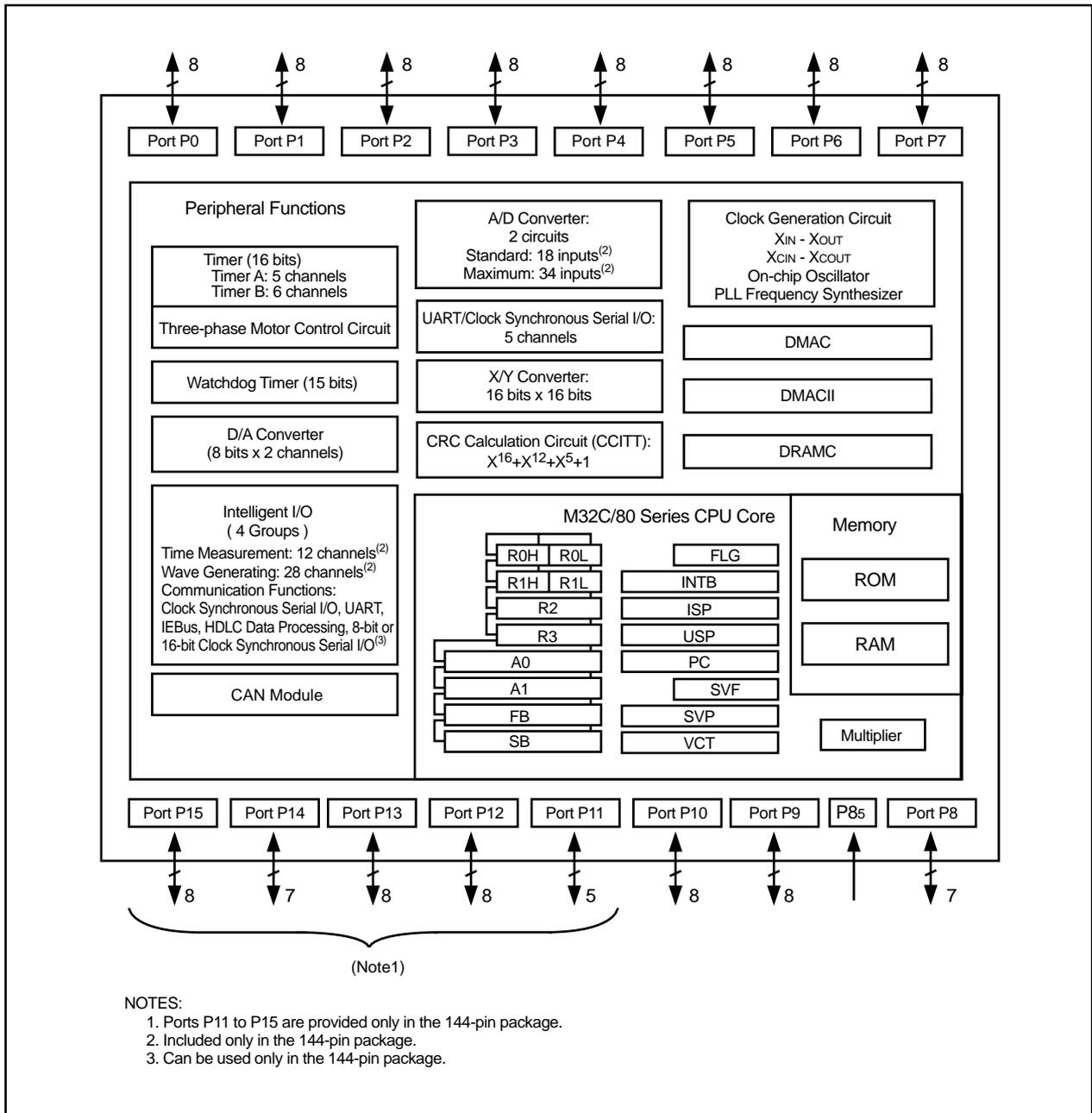


Figure 1.1 M32C/83 Group (M32C/83, M32C/83T) Block Diagram

1.4 Product Information

Table 1.3 lists the product information. Figure 1.2 shows the product numbering system.

Table 1.3 M32C/83 Group (1) (M32C/83) As of January, 2006

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30835FJGP	PLQP0144KA-A (144P6Q-A)	512K	31K	Flash Memory
M30833FJGP	PLQP0100KB-A (100P6Q-A)			
M30833FJFP	PRQP0100JB-A (100P6S-A)			

Table 1.3 M32C/83 Group (2) (T Version, M32C/83T) As of January, 2006

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30833FJTGP	PLQP0100KB-A (100P6Q-A)	512K	31K	Flash Memory T Version (High-reliability 85°C Version)

Please contact our sales office for V version information.

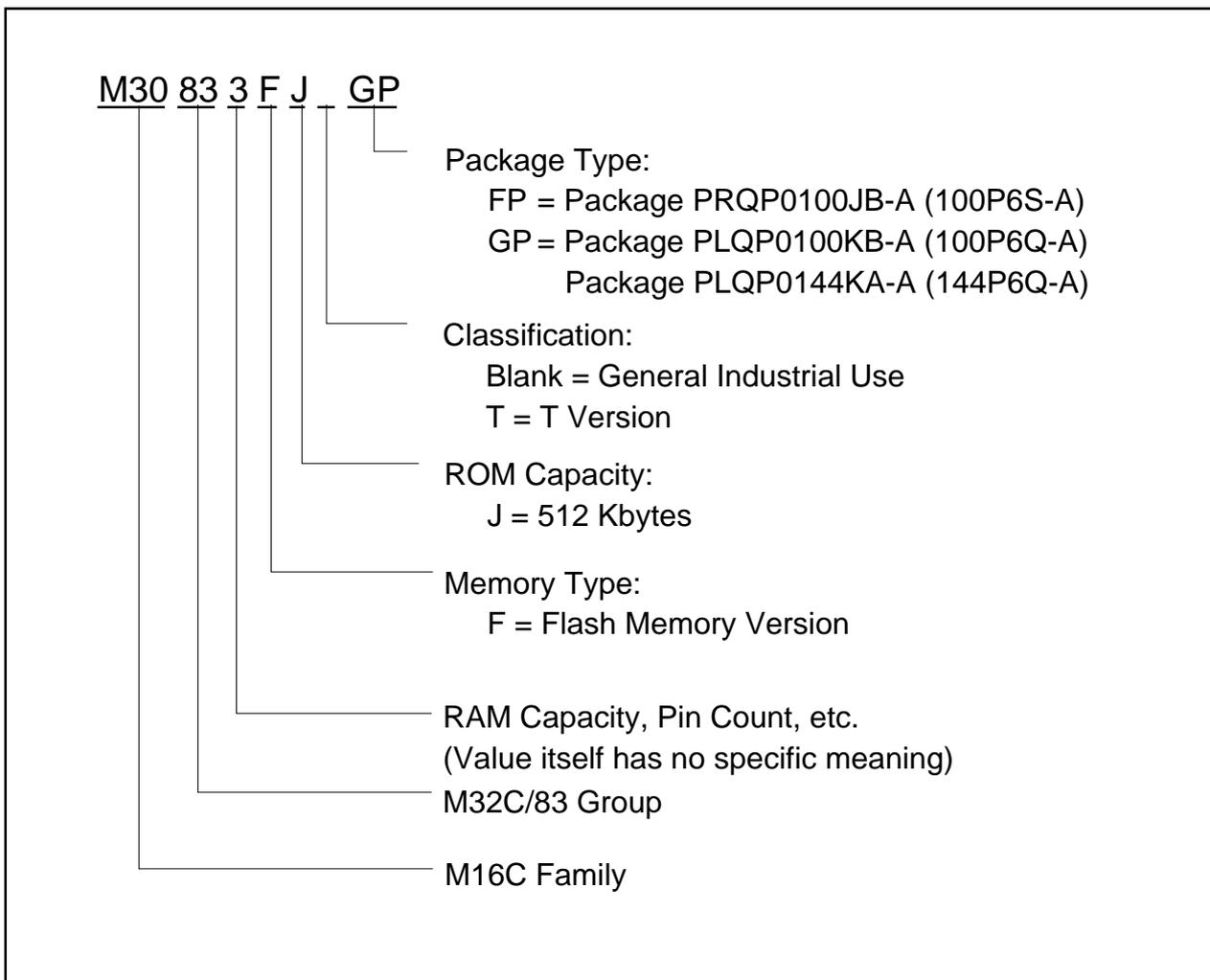


Figure 1.2 Product Numbering System

Address	Register	Symbol	Value after RESET
00F0 ₁₆	Group 0 Data Compare Register 0	G0CMP0	XX ₁₆
00F1 ₁₆	Group 0 Data Compare Register 1	G0CMP1	XX ₁₆
00F2 ₁₆	Group 0 Data Compare Register 2	G0CMP2	XX ₁₆
00F3 ₁₆	Group 0 Data Compare Register 3	G0CMP3	XX ₁₆
00F4 ₁₆	Group 0 Data Mask Register 0	G0MSK0	XX ₁₆
00F5 ₁₆	Group 0 Data Mask Register 1	G0MSK1	XX ₁₆
00F6 ₁₆			
00F7 ₁₆			
00F8 ₁₆ 00F9 ₁₆	Group 0 Receive CRC Code Register	G0RCRC	XX ₁₆ XX ₁₆
00FA ₁₆ 00FB ₁₆	Group 0 Transmit CRC Code Register	G0TCRC	00 ₁₆ 00 ₁₆
00FC ₁₆	Group 0 SI/O Extended Mode Register	G0EMR	00 ₁₆
00FD ₁₆	Group 0 SI/O Extended Receive Control Register	G0ERC	00 ₁₆
00FE ₁₆	Group 0 SI/O Special Communication Interrupt Detect Register	G0IRF	0000 00XX ₂
00FF ₁₆	Group 0 SI/O Extended Transmit Control Register	G0ETC	0000 0XXX ₂
0100 ₁₆ 0101 ₁₆	Group 1 Time Measurement/Waveform Generating Register 0	G1TM0/G1PO0	XX ₁₆ XX ₁₆
0102 ₁₆ 0103 ₁₆	Group 1 Time Measurement/Waveform Generating Register 1	G1TM1/G1PO1	XX ₁₆ XX ₁₆
0104 ₁₆ 0105 ₁₆	Group 1 Time Measurement/Waveform Generating Register 2	G1TM2/G1PO2	XX ₁₆ XX ₁₆
0106 ₁₆ 0107 ₁₆	Group 1 Time Measurement/Waveform Generating Register 3	G1TM3/G1PO3	XX ₁₆ XX ₁₆
0108 ₁₆ 0109 ₁₆	Group 1 Time Measurement/Waveform Generating Register 4	G1TM4/G1PO4	XX ₁₆ XX ₁₆
010A ₁₆ 010B ₁₆	Group 1 Time Measurement/Waveform Generating Register 5	G1TM5/G1PO5	XX ₁₆ XX ₁₆
010C ₁₆ 010D ₁₆	Group 1 Time Measurement/Waveform Generating Register 6	G1TM6/G1PO6	XX ₁₆ XX ₁₆
010E ₁₆ 010F ₁₆	Group 1 Time Measurement/Waveform Generating Register 7	G1TM7/G1PO7	XX ₁₆ XX ₁₆
0110 ₁₆	Group 1 Waveform Generating Control Register 0	G1POCR0	0X00 X000 ₂
0111 ₁₆	Group 1 Waveform Generating Control Register 1	G1POCR1	0X00 X000 ₂
0112 ₁₆	Group 1 Waveform Generating Control Register 2	G1POCR2	0X00 X000 ₂
0113 ₁₆	Group 1 Waveform Generating Control Register 3	G1POCR3	0X00 X000 ₂
0114 ₁₆	Group 1 Waveform Generating Control Register 4	G1POCR4	0X00 X000 ₂
0115 ₁₆	Group 1 Waveform Generating Control Register 5	G1POCR5	0X00 X000 ₂
0116 ₁₆	Group 1 Waveform Generating Control Register 6	G1POCR6	0X00 X000 ₂
0117 ₁₆	Group 1 Waveform Generating Control Register 7	G1POCR7	0X00 X000 ₂
0118 ₁₆	Group 1 Time Measurement Control Register 0	G1TMCR0	00 ₁₆
0119 ₁₆	Group 1 Time Measurement Control Register 1	G1TMCR1	00 ₁₆
011A ₁₆	Group 1 Time Measurement Control Register 2	G1TMCR2	00 ₁₆
011B ₁₆	Group 1 Time Measurement Control Register 3	G1TMCR3	00 ₁₆
011C ₁₆	Group 1 Time Measurement Control Register 4	G1TMCR4	00 ₁₆
011D ₁₆	Group 1 Time Measurement Control Register 5	G1TMCR5	00 ₁₆
011E ₁₆	Group 1 Time Measurement Control Register 6	G1TMCR6	00 ₁₆
011F ₁₆	Group 1 Time Measurement Control Register 7	G1TMCR7	00 ₁₆

X: Indeterminate

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Address	Register	Symbol	Value after RESET
0180 ₁₆ 0181 ₁₆	Group 3 Waveform Generating Register 0	G3PO0	XX ₁₆ XX ₁₆
0182 ₁₆ 0183 ₁₆	Group 3 Waveform Generating Register 1	G3PO1	XX ₁₆ XX ₁₆
0184 ₁₆ 0185 ₁₆	Group 3 Waveform Generating Register 2	G3PO2	XX ₁₆ XX ₁₆
0186 ₁₆ 0187 ₁₆	Group 3 Waveform Generating Register 3	G3PO3	XX ₁₆ XX ₁₆
0188 ₁₆ 0189 ₁₆	Group 3 Waveform Generating Register 4	G3PO4	XX ₁₆ XX ₁₆
018A ₁₆ 018B ₁₆	Group 3 Waveform Generating Register 5	G3PO5	XX ₁₆ XX ₁₆
018C ₁₆ 018D ₁₆	Group 3 Waveform Generating Register 6	G3PO6	XX ₁₆ XX ₁₆
018E ₁₆ 018F ₁₆	Group 3 Waveform Generating Register 7	G3PO7	XX ₁₆ XX ₁₆
0190 ₁₆	Group 3 Waveform Generating Control Register 0	G3POCR0	00 ₁₆
0191 ₁₆	Group 3 Waveform Generating Control Register 1	G3POCR1	00 ₁₆
0192 ₁₆	Group 3 Waveform Generating Control Register 2	G3POCR2	00 ₁₆
0193 ₁₆	Group 3 Waveform Generating Control Register 3	G3POCR3	00 ₁₆
0194 ₁₆	Group 3 Waveform Generating Control Register 4	G3POCR4	00 ₁₆
0195 ₁₆	Group 3 Waveform Generating Control Register 5	G3POCR5	00 ₁₆
0196 ₁₆	Group 3 Waveform Generating Control Register 6	G3POCR6	00 ₁₆
0197 ₁₆	Group 3 Waveform Generating Control Register 7	G3POCR7	00 ₁₆
0198 ₁₆ 0199 ₁₆	Group 3 Waveform Generating Mask Register 4	G3MK4	XX ₁₆ XX ₁₆
019A ₁₆ 019B ₁₆	Group 3 Waveform Generating Mask Register 5	G3MK5	XX ₁₆ XX ₁₆
019C ₁₆ 019D ₁₆	Group 3 Waveform Generating Mask Register 6	G3MK6	XX ₁₆ XX ₁₆
019E ₁₆ 019F ₁₆	Group 3 Waveform Generating Mask Register 7	G3MK7	XX ₁₆ XX ₁₆
01A0 ₁₆ 01A1 ₁₆	Group 3 Base Timer Register	G3BT	XX ₁₆ XX ₁₆
01A2 ₁₆	Group 3 Base Timer Control Register 0	G3BCR0	00 ₁₆
01A3 ₁₆	Group 3 Base Timer Control Register 1	G3BCR1	00 ₁₆
01A4 ₁₆			
01A5 ₁₆			
01A6 ₁₆	Group 3 Function Enable Register	G3FE	00 ₁₆
01A7 ₁₆	Group 3 RTP Output Buffer Register	G3RTP	00 ₁₆
01A8 ₁₆			
01A9 ₁₆			
01AA ₁₆			
01AB ₁₆			
01AC ₁₆			
01AD ₁₆	Group 3 SI/O Communication Flag Register	G3FLG	XXXX XXX0 ₂
01AE ₁₆			
01AF ₁₆			

X: Indeterminate

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Address	Register	Symbol	Value after RESET
02F0 ₁₆			
02F1 ₁₆			
02F2 ₁₆			
02F3 ₁₆			
02F4 ₁₆	UART4 Special Mode Register 4	U4SMR4	00 ₁₆
02F5 ₁₆	UART4 Special Mode Register 3	U4SMR3	00 ₁₆
02F6 ₁₆	UART4 Special Mode Register 2	U4SMR2	00 ₁₆
02F7 ₁₆	UART4 Special Mode Register	U4SMR	00 ₁₆
02F8 ₁₆	UART4 Transmit/Receive Mode Register	U4MR	00 ₁₆
02F9 ₁₆	UART4 Baud Rate Register	U4BRG	XX ₁₆
02FA ₁₆	UART4 Transmit Buffer Register	U4TB	XX ₁₆
02FB ₁₆			XX ₁₆
02FC ₁₆	UART4 Transmit/Receive Control Register 0	U4C0	0000 1000 ₂
02FD ₁₆	UART4 Transmit/Receive Control Register 1	U4C1	0000 0010 ₂
02FE ₁₆	UART4 Receive Buffer Register	U4RB	XX ₁₆
02FF ₁₆			XX ₁₆
0300 ₁₆	Timer B3, B4, B5 Count Start Flag	TBSR	000X XXXX ₂
0301 ₁₆			
0302 ₁₆	Timer A1-1 Register	TA11	XX ₁₆
0303 ₁₆			XX ₁₆
0304 ₁₆	Timer A2-1 Register	TA21	XX ₁₆
0305 ₁₆			XX ₁₆
0306 ₁₆	Timer A4-1 Register	TA41	XX ₁₆
0307 ₁₆			XX ₁₆
0308 ₁₆	Three-Phase PWM Control Register 0	INVC0	00 ₁₆
0309 ₁₆	Three-Phase PWM Control Register 1	INVC1	00 ₁₆
030A ₁₆	Three-Phase output Buffer Register 0	IDB0	XX11 1111 ₂
030B ₁₆	Three-Phase output Buffer Register 1	IDB1	XX11 1111 ₂
030C ₁₆	Dead Time Timer	DTT	XX ₁₆
030D ₁₆	Timer B2 Interrupt Generating Frequency Set Counter	ICTB2	XX ₁₆
030E ₁₆			
030F ₁₆			
0310 ₁₆	Timer B3 Register	TB3	XX ₁₆
0311 ₁₆			XX ₁₆
0312 ₁₆	Timer B4 Register	TB4	XX ₁₆
0313 ₁₆			XX ₁₆
0314 ₁₆	Timer B5 Register	TB5	XX ₁₆
0315 ₁₆			XX ₁₆
0316 ₁₆			
0317 ₁₆			
0318 ₁₆			
0319 ₁₆			
031A ₁₆			
031B ₁₆	Timer B3 Mode Register	TB3MR	00XX 0000 ₂
031C ₁₆	Timer B4 Mode Register	TB4MR	00XX 0000 ₂
031D ₁₆	Timer B5 Mode Register	TB5MR	00XX 0000 ₂
031E ₁₆			
031F ₁₆	External Interrupt Cause Select Register	IFSR	00 ₁₆

X: Indeterminate

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Address	Register	Symbol	Value after RESET
0380 ₁₆ 0381 ₁₆	A/D0 Register 0	AD00	XX ₁₆ XX ₁₆
0382 ₁₆ 0383 ₁₆	A/D0 Register 1	AD01	XX ₁₆ XX ₁₆
0384 ₁₆ 0385 ₁₆	A/D0 Register 2	AD02	XX ₁₆ XX ₁₆
0386 ₁₆ 0387 ₁₆	A/D0 Register 3	AD03	XX ₁₆ XX ₁₆
0388 ₁₆ 0389 ₁₆	A/D0 Register 4	AD04	XX ₁₆ XX ₁₆
038A ₁₆ 038B ₁₆	A/D0 Register 5	AD05	XX ₁₆ XX ₁₆
038C ₁₆ 038D ₁₆	A/D0 Register 6	AD06	XX ₁₆ XX ₁₆
038E ₁₆ 038F ₁₆	A/D0 Register 7	AD07	XX ₁₆ XX ₁₆
0390 ₁₆			
0391 ₁₆			
0392 ₁₆			
0393 ₁₆			
0394 ₁₆ 0395 ₁₆	A/D0 Control Register 2	AD0CON2	X000 0000 ₂
0396 ₁₆	A/D0 Control Register 0	AD0CON0	00 ₁₆
0397 ₁₆	A/D0 Control Register 1	AD0CON1	00 ₁₆
0398 ₁₆ 0399 ₁₆	D/A Register 0	DA0	XX ₁₆
039A ₁₆ 039B ₁₆	D/A Register 1	DA1	XX ₁₆
039C ₁₆ 039D ₁₆	D/A Control Register	DACON	XXXX XX00 ₂
039E ₁₆			
039F ₁₆			

X: Indeterminate

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Table 5.4 A/D Conversion Characteristics (V_{CC} = AV_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V at Topr = -20 to 85°C, f(X_{IN}) = 32MHz unless otherwise specified)

Symbol	Parameter	Measurement Condition	Standard			Unit	
			Min	Typ	Max		
-	Resolution	V _{REF} =V _{CC}			10	Bits	
INL	Integral Nonlinearity Error	V _{REF} =V _{CC} =5V	AN ₀ to AN ₇ AN _{EX0} , AN _{EX1}			±3	LSB
							LSB
					±7	LSB	
						LSB	
DNL	Differential Nonlinearity Error				±1	LSB	
-	Offset Error				±3	LSB	
-	Gain Error				±3	LSB	
R _{LADDER}	Resistor Ladder	V _{REF} =V _{CC}	8		40	kΩ	
t _{CONV}	10-bit Conversion Time		2.1			μs	
t _{CONV}	8-bit Conversion Time		1.8			μs	
t _{SAMP}	Sample Time		0.2			μs	
V _{REF}	Reference Voltage		2		V _{CC}	V	
V _{IA}	Analog Input Voltage		0		V _{REF}	V	

NOTES:

1. Divide f(X_{IN}), if exceeding 16 MHz, to keep φ_{AD} frequency at 16 MHz or less.

Table 5.5 D/A Conversion Characteristics (V_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V at Topr = -20 to 85°C, f(X_{IN}) = 32MHz unless otherwise specified)

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min	Typ	Max	
-	Resolution				8	Bits
-	Absolute Accuracy				1.0	%
t _{SU}	Setup Time				3	μs
R _O	Output Resistance		4	10	20	kΩ
I _{VREF}	Reference Power Supply Input Current	(Note 1)			1.5	mA

NOTES:

1. Measurement results when using one D/A converter. The DAI register (i=0, 1) of the D/A converter not being used is set to "00₁₆". The resistor ladder in the A/D converter is excluded. I_{VREF} flows even if the VCUT bit in the ADiCON1 register is set to "0" (no V_{REF} connection).

Table 5.6 Flash Memory Version Electrical Characteristics

Parameter	Standard			Unit
	Min	Typ	Max	
Program Time (per page)		8	120	ms
Block Erase Time (per block)		50	600	ms

NOTES:

1. V_{CC}= 4.2 to 5.5V (through VDC), 3.0 to 3.6V (not through VDC) at Topr= 0 to 60° C, unless otherwise specified

Timing Requirements**(VCC = 4.2 to 5.5V, VSS = 0V at Topr = -20 to 85°C unless otherwise specified)****Table 5.9 Timer A Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	100		ns
tw(TAH)	TAin Input High ("H") Pulse Width	40		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	40		ns

Table 5.10 Timer A Input (Gate Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	400		ns
tw(TAH)	TAin Input High ("H") Pulse Width	200		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	200		ns

Table 5.11 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	200		ns
tw(TAH)	TAin Input High ("H") Pulse Width	100		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	100		ns

Table 5.12 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tw(TAH)	TAin Input High ("H") Pulse Width	100		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	100		ns

Table 5.13 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(UP)	TAiout Input Cycle Time	2000		ns
tw(UPH)	TAiout Input High ("H") Pulse Width	1000		ns
tw(UPL)	TAiout Input Low ("L") Pulse Width	1000		ns
tsu(UP-TIN)	TAiout Input Setup Time	400		ns
th(TIN-UP)	TAiout Input Hold Time	400		ns

Timing Requirements**(VCC = 4.2 to 5.5V, VSS = 0V at Topr = -20 to 85°C unless otherwise specified)****Table 5.14 Timer B Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TB)	TBiN Input Cycle Time (counted on one edge)	100		ns
tw(TBH)	TBiN Input High ("H") Pulse Width (counted on one edge)	40		ns
tw(TBL)	TBiN Input Low ("L") Pulse Width (counted on one edge)	40		ns
tc(TB)	TBiN Input Cycle Time (counted on both edges)	200		ns
tw(TBH)	TBiN Input High ("H") Pulse Width (counted on both edges)	80		ns
tw(TBL)	TBiN Input Low ("L") Pulse Width (counted on both edges)	80		ns

Table 5.15 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TB)	TBiN Input Cycle Time	400		ns
tw(TBH)	TBiN Input High ("H") Pulse Width	200		ns
tw(TBL)	TBiN Input Low ("L") Pulse Width	200		ns

Table 5.16 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TB)	TBiN Input Cycle Time	400		ns
tw(TBH)	TBiN Input High ("H") Pulse Width	200		ns
tw(TBL)	TBiN Input Low ("L") Pulse Width	200		ns

Table 5.17 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(AD)	$\overline{\text{ADTRG}}$ Input Cycle Time (required for re-trigger)	1000		ns
tw(ADL)	$\overline{\text{ADTRG}}$ Input Low ("L") Pulse Width	125		ns

Table 5.18 Serial I/O

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(CLK)	CLKi Input Cycle Time	200		ns
tw(CLKH)	CLKi Input High ("H") Pulse Width	100		ns
tw(CLKL)	CLKi Input Low ("L") Pulse Width	100		ns
td(CQ)	TxDi Output Delay Time		80	ns
th(CQ)	TxDi Hold Time	0		ns
tsu(DQ)	RxDi Input Set Up Time	30		ns
th(CQ)	RxDi Input Hold Time	90		ns

Table 5.19 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min	Max	
tw(INH)	$\overline{\text{INTi}}$ Input High ("H") Pulse Width	250		ns
tw(INL)	$\overline{\text{INTi}}$ Input Low ("L") Pulse Width	250		ns

Switching Characteristics(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = -20 to 85°C unless otherwise specified)**Table 5.20 Memory Expansion Mode and Microprocessor Mode (with No Wait State)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
td(BCLK-AD)	Address Output Delay Time	See Figure 5.1		18	ns
th(BCLK-AD)	Address Output Hold Time (BCLK standard)		-3		ns
th(RD-AD)	Address Output Hold Time (RD standard)		0		ns
th(WR-AD)	Address Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-CS)	Chip-select Signal Output Delay Time			18	ns
th(BCLK-CS)	Chip-select Signal Output Hold Time (BCLK standard)		-3		ns
th(RD-CS)	Chip-select Signal Output Hold Time (RD standard)		0		ns
th(WR-CS)	Chip-select Signal Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-ALE)	ALE Signal Output Delay Time			18	ns
th(BCLK-ALE)	ALE Signal Output Hold Time		-2		ns
td(BCLK-RD)	RD Signal Output Delay Time			18	ns
th(BCLK-RD)	RD Signal Output Hold Time		-5		ns
td(BCLK-WR)	WR Signal Output Delay Time			18	ns
th(BCLK-WR)	WR Signal Output Hold Time		-3		ns
td(DB-WR)	Data Output Delay Time (WR standard)		(Note 1)		ns
th(WR-DB)	Data Output Hold Time (WR standard)		(Note 1)		ns
tw(WR)	WR Output Width		(Note 1)		ns

NOTES:

- Values can be obtained from the following equations, according to BCLK frequency.

$$td(DB - WR) = \frac{10^9}{f(BCLK)} - 20 \quad [ns]$$

$$th(WR - DB) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$tw(WR) = \frac{10^9}{f(BCLK) \times 2} - 15 \quad [ns]$$

Switching Characteristics(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = -20 to 85°C unless otherwise specified)**Table 5.21 Memory Expansion Mode and Microprocessor Mode
(With a Wait State, Accessing an External Memory)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
t _{d(BCLK-AD)}	Address Output Delay Time	See Figure 5.1		18	ns
t _{h(BCLK-AD)}	Address Output Hold Time (BCLK standard)		-3		ns
t _{h(RD-AD)}	Address Output Hold Time (RD standard)		0		ns
t _{h(WR-AD)}	Address Output Hold Time (WR standard)		(Note 1)		ns
t _{d(BCLK-CS)}	Chip-select Signal Output Delay Time			18	ns
t _{h(BCLK-CS)}	Chip-select Signal Output Hold Time (BCLK standard)		-3		ns
t _{h(RD-CS)}	Chip-select Signal Output Hold Time (RD standard)		0		ns
t _{h(WR-CS)}	Chip-select Signal Output Hold Time (WR standard)		(Note 1)		ns
t _{d(BCLK-ALE)}	ALE Signal Output Delay Time			18	ns
t _{h(BCLK-ALE)}	ALE Signal Output Hold Time		-2		ns
t _{d(BCLK-RD)}	RD Signal Output Delay Time			18	ns
t _{h(BCLK-RD)}	RD Signal Output Hold Time		-5		ns
t _{d(BCLK-WR)}	WR Signal Output Delay Time			18	ns
t _{h(BCLK-WR)}	WR Signal Output Hold Time		-3		ns
t _{d(DB-WR)}	Data Output Delay Time (WR standard)		(Note 1)		ns
t _{h(WR-DB)}	Data Output Hold Time (WR standard)		(Note 1)		ns
t _{w(WR)}	WR Output Width		(Note 1)		ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency.

$$t_{d(DB-WR)} = \frac{10^9 \times n}{f(\text{BCLK})} - 20 \quad [\text{ns}] \quad (n=1 \text{ with 1 wait state, } n=2 \text{ with 2 wait states} \\ \text{and } n=3 \text{ with 3 wait states})$$

$$t_{h(WR-DB)} = \frac{10^9}{f(\text{BCLK}) \times 2} - 10 \quad [\text{ns}]$$

$$t_{h(WR-AD)} = \frac{10^9}{f(\text{BCLK}) \times 2} - 10 \quad [\text{ns}]$$

$$t_{h(WR-CS)} = \frac{10^9}{f(\text{BCLK}) \times 2} - 10 \quad [\text{ns}]$$

$$t_{w(WR)} = \frac{10^9 \times n}{f(\text{BCLK}) \times 2} - 15 \quad [\text{ns}] \quad (n=1 \text{ with 1 wait state, } n=3 \text{ with 2 wait states} \\ \text{and } n=5 \text{ with 3 wait states})$$

Switching Characteristics(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = –20 to 85°C unless otherwise specified)**Table 5.23 Memory Expansion Mode and Microprocessor Mode
(With a Wait State, Accessing an External Memory and Selecting the DRAM Space)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
td(BCLK-RAD)	Row Address Output Delay Time	See Figure 5.1		18	ns
th(BCLK-RAD)	Row Address Output Hold Time (BCLK standard)		-3		ns
td(BCLK-CAD)	Column Address Output Delay Time			18	ns
th(BCLK-CAD)	Column Address Output Hold Time (BCLK standard)		-3		ns
th(RAS-RAD)	Row Address Output Hold Time after RAS Output		(Note 1)		ns
td(BCLK-RAS)	RAS Output Delay Time (BCLK standard)			18	ns
th(BCLK-RAS)	RAS Output Hold Time (BCLK standard)		-3		ns
tRP	RAS High ("H") Hold Time		(Note 1)		ns
td(BCLK-CAS)	CAS Output Delay Time (BCLK standard)			18	ns
th(BCLK-CAS)	CAS Output Hold Time (BCLK standard)		-3		ns
td(BCLK-DW)	DW Output Delay Time (BCLK standard)			18	ns
th(BCLK-DW)	DW Output Hold Time (BCLK standard)		-5		ns
tsu(DB-CAS)	CAS Output Setup Time after DB Output		(Note 1)		ns
th(BCLK-DB)	DB Signal Output Hold Time (BCLK standard)		-7		ns
tsu(CAS-RAS)	CAS Output Setup Time before RAS Output (refresh)		(Note 1)		ns

NOTES:

1. Values can be obtained from the following equation, according to BCLK frequency.

$$th(RAS - RAD) = \frac{10^9}{f(BCLK) \times 2} - 13 \quad [ns]$$

$$tRP = \frac{10^9 \times 3}{f(BCLK) \times 2} - 20 \quad [ns]$$

$$tsu(DB - CAS) = \frac{10^9}{f(BCLK)} - 20 \quad [ns]$$

$$tsu(CAS - RAS) = \frac{10^9}{f(BCLK) \times 2} - 13 \quad [ns]$$

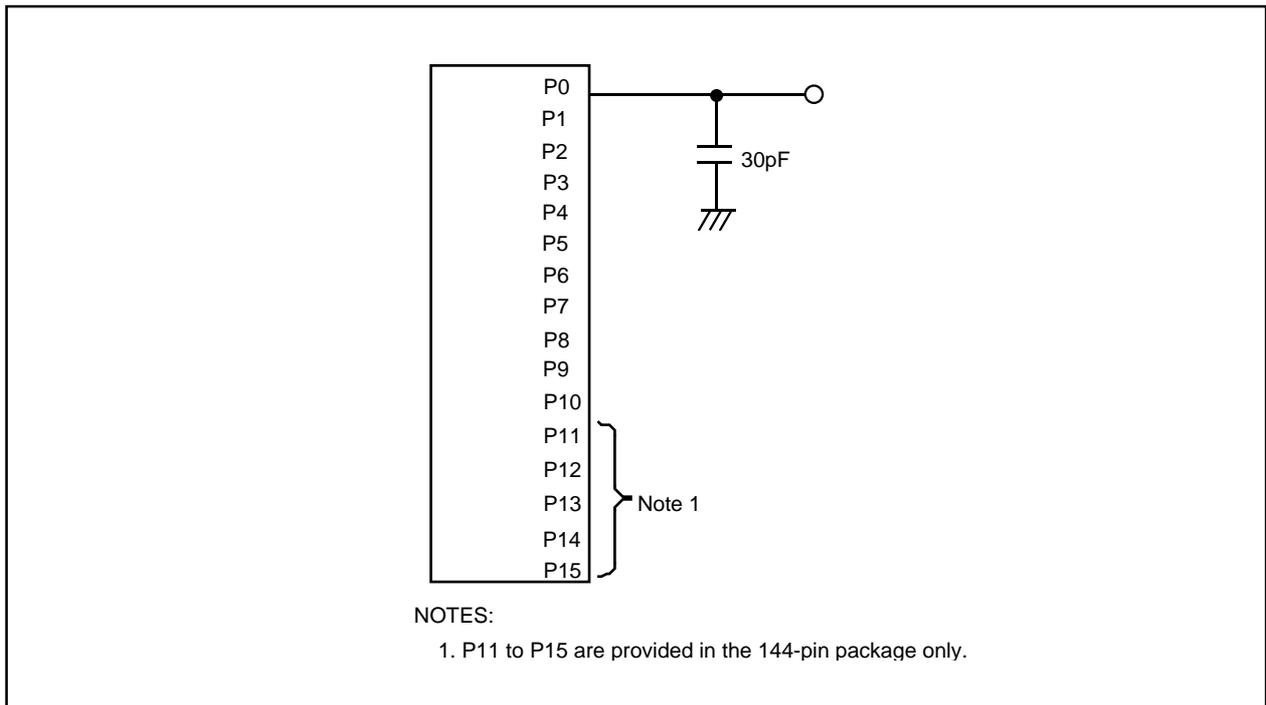


Figure 5.1 P0 to P15 Measurement Circuit

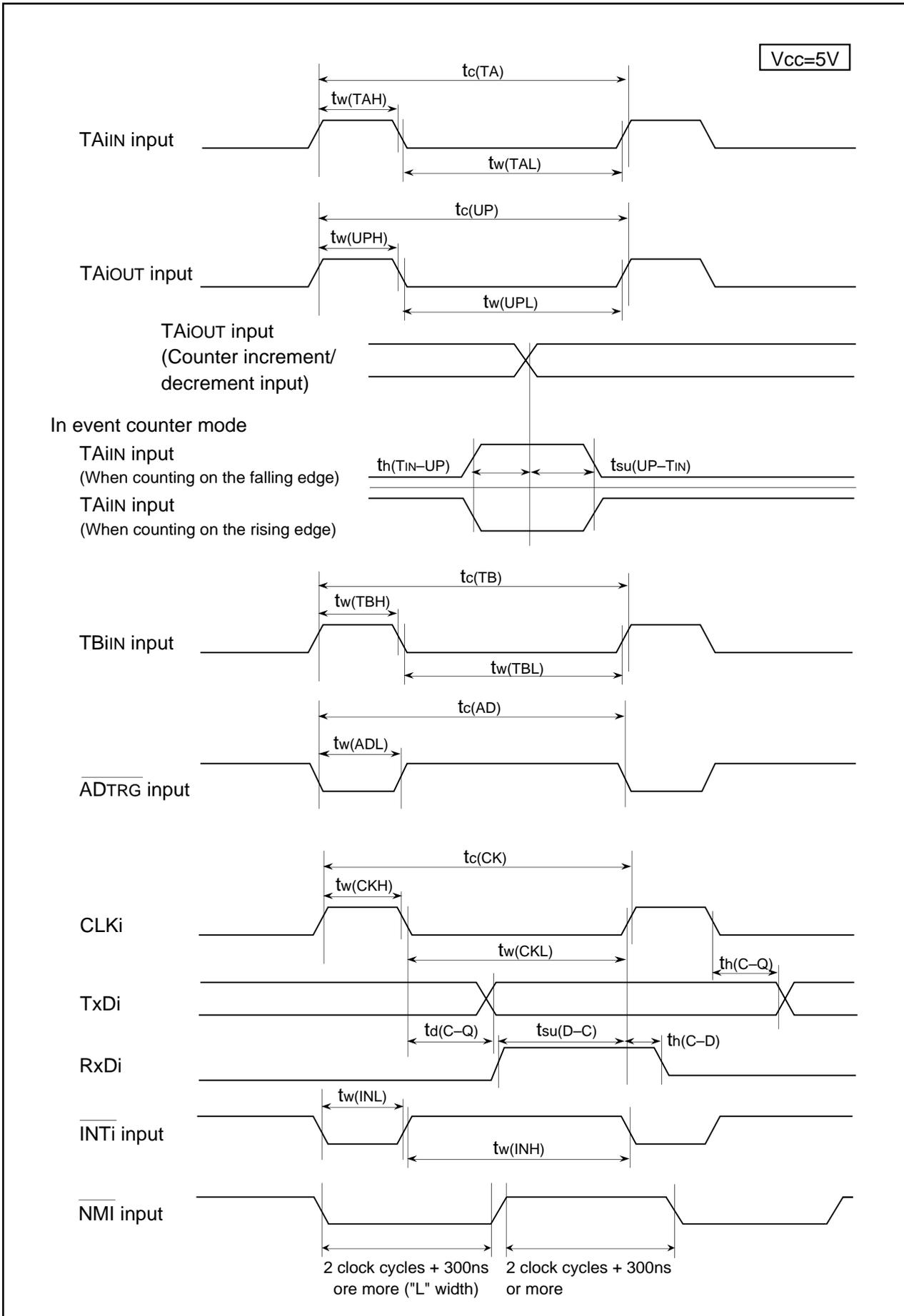


Figure 5.8 V_{CC}=5V Timing Diagram (7)

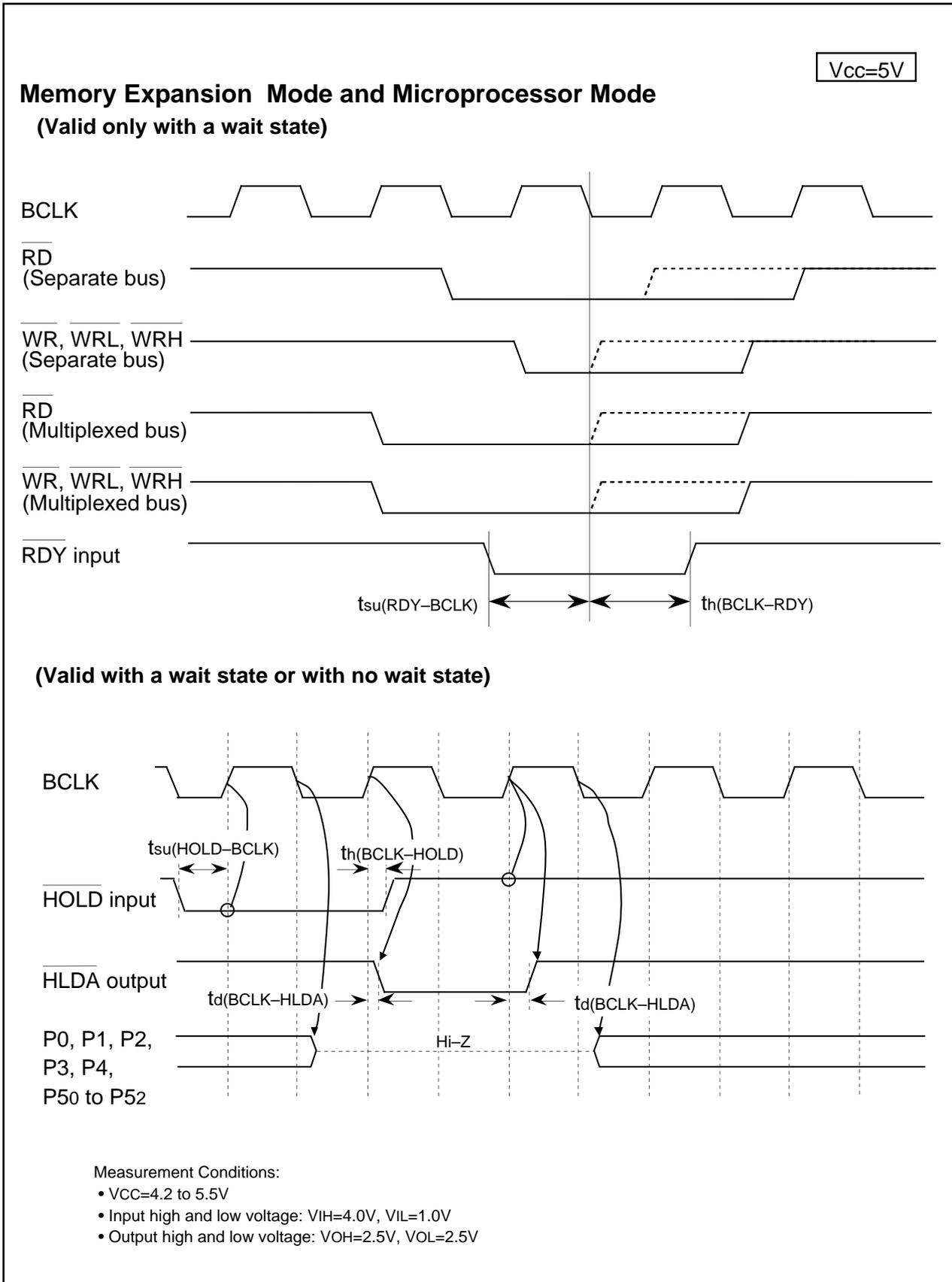


Figure 5.9 V_{CC}=5V Timing Diagram (8)

Timing Requirements**(VCC = 3.0 to 3.6V, VSS = 0V at Topr = -20 to 85°C unless otherwise specified)****Table 5.30 Timer A Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAiIn Input Cycle Time	100		ns
tw(TAH)	TAiIn Input High ("H") Pulse Width	40		ns
tw(TAL)	TAiIn Input Low ("L") Pulse Width	40		ns

Table 5.31 Timer A Input (Gate Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAiIn Input Cycle Time	400		ns
tw(TAH)	TAiIn Input High ("H") Pulse Width	200		ns
tw(TAL)	TAiIn Input Low ("L") Pulse Width	200		ns

Table 5.32 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAiIn Input Cycle Time	200		ns
tw(TAH)	TAiIn Input High ("H") Pulse Width	100		ns
tw(TAL)	TAiIn Input Low ("L") Pulse Width	100		ns

Table 5.33 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tw(TAH)	TAiIn Input High ("H") Pulse Width	100		ns
tw(TAL)	TAiIn Input Low ("L") Pulse Width	100		ns

Table 5.34 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(UP)	TAiOUT Input Cycle Time	2000		ns
tw(UPH)	TAiOUT Input High ("H") Pulse Width	1000		ns
tw(UPL)	TAiOUT Input Low ("L") Pulse Width	1000		ns
tsu(UP-TIN)	TAiOUT Input Setup Time	400		ns
th(TIN-UP)	TAiOUT Input Hold Time	400		ns

**Table 5.47 Electrical Characteristics (V_{CC} = 4.2 to 5.5 V, V_{SS} = 0V
at Topr = -40 to 85°C(T version), f(X_{IN})=32MHz unless otherwise specified)**

Symbol	Parameter		Condition	Standard			Unit
				Min	Typ	Max	
V _{OH}	Output High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OH} =-5mA	V _{CC} -2.0			V
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OH} =-200μA	V _{CC} -0.3			
		X _{OUT}	I _{OH} =-1mA	3.0			V
		X _{COU} T	No load applied		3.3		V
V _{OL}	Output Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =5mA			2.0	V
		P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =200μA			0.45	
		X _{OUT}	I _{OL} =1mA			2.0	V
		X _{COU} T	No load applied		0		V
V _{T+} -V _{T-}	Hysteresis	HOLD, RDY, TA0 _{IN} -TA4 _{IN} , TB0 _{IN} -TB5 _{IN} , INT0-INT5, AD _{TRG} , CTS0-CTS4, CLK0-CLK4, TA0 _{OUT} -TA4 _{OUT} , NMI, KI0-KI3, RxD0-RxD4, SCL0-SCL4, SDA0-SDA4		0.2		1.0	V
		RESET		0.2		1.8	
I _{IH}	Input High ("H") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =5V			5.0	μA
I _{IL}	Input Low ("L") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =0V			-5.0	μA
R _{PULLUP}	Pull-up Resistance	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	V _I =0V	30	50	167	kΩ
R _{fXIN}	Feedback Resistance	X _{IN}			1.5		MΩ
R _{fXCIN}	Feedback Resistance	X _{CIN}			10		MΩ
V _{RAM}	RAM Standby Voltage			2.5			V
I _{CC}	Power Supply Current	Measurement conditions: In single-chip mode, output pins are left open and other pins are connected to V _{SS}	f(X _{IN})=32 MHz, square wave, no division		40	54	mA
			f(X _{CIN})=32 kHz, with a wait state, Topr=25° C		470		μA
			Topr=25° C when the clock stops		0.4	20	μA

NOTES:

- P11 to P15 are provided in the 144-pin package only.

Table 5.48 A/D Conversion Characteristics (V_{CC} = AV_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V at Topr = -40 to 85°C (T version), f(X_{IN}) = 32MHz unless otherwise specified)

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min	Typ	Max	
-	Resolution	V _{REF} =V _{CC}			10	Bits
INL	Integral Nonlinearity Error	V _{REF} =V _{CC} =5V	AN ₀ to AN ₇ AN _{EX0} , AN _{EX1}		±3	LSB
			External op-amp connection mode		±7	LSB
DNL	Differential Nonlinearity Error				±1	LSB
-	Offset Error				±3	LSB
-	Gain Error				±3	LSB
RLADDER	Resistor Ladder	V _{REF} =V _{CC}	8		40	kΩ
t _{CONV}	10-bit Conversion Time		2.1			μs
t _{CONV}	8-bit Conversion Time		1.8			μs
t _{SAMP}	Sample Time		0.2			μs
V _{REF}	Reference Voltage		2		V _{CC}	V
V _{IA}	Analog Input Voltage		0		V _{REF}	V

NOTES:

1. Divide f(X_{IN}), if exceeding 16 MHz, to keep φ_{AD} frequency at 16 MHz or less.

Table 5.49 D/A Conversion Characteristics (V_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V at Topr = -40 to 85°C (T version), f(X_{IN}) = 32MHz unless otherwise specified)

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min	Typ	Max	
-	Resolution				8	Bits
-	Absolute Accuracy				1.0	%
t _{SU}	Setup Time				3	μs
R _O	Output Resistance		4	10	20	kΩ
I _{VREF}	Reference Power Supply Input Current	(Note 1)			1.5	mA

NOTES:

1. Measurement results when using one D/A converter. The DA_i register (i=0, 1) of the D/A converter not being used is set to "0016". The resistor ladder in the A/D converter is excluded. I_{VREF} flows even if the VCUT bit in the ADiCON1 register is set to "0" (no V_{REF} connection).

Table 5.50 Flash Memory Version Electrical Characteristics

Parameter	Standard			Unit
	Min	Typ	Max	
Program Time (per page)		8	120	ms
Block Erase Time (per block)		50	600	ms

NOTES:

1. V_{CC}= 4.2 to 5.5V at Topr= 0 to 60° C, unless otherwise specified

REVISION HISTORY

M32C/83 GROUP (M32C/83, M32C/83T) Datasheet

Rev.	Date	Description	
		Page	Summary
		72	<ul style="list-style-type: none"> • Table 5.44 Memory Expansion Mode and Microprocessor Mode Symbols for Row Address Output Delay Time and for Row Address Output Hold Time (BCLK standard) modified
		79	<ul style="list-style-type: none"> • Figure 5.8 Vcc=3.3 V Timing Diagram (7) Timing for $\overline{\text{NMI}}$ input added
		81-89	<ul style="list-style-type: none"> • 5.2 Electrical Characteristics (M32C/83T) Newly added